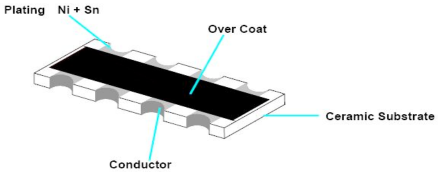
MATERIAL DECLARATION SHEET

BOURNS®

Material Number	CAY16-F/J4 (LF) series		
Product Line	Chip Resistor Array		
Compliance Date	**2012/07/18**		
RoHS Compliant	Yes	MSL	**1**



No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00731154	Aluminum oxide	1344-28-1	96%	80.42%	83.77%
				Silicon dioxide	14808-60-7	4%	3.35%	
2	Conductor Layer	Other	0.00010905	Silver	7440-22-4	95%	1.19%	1.25%
				Glass	65997-18-4	5%	0.06%	
3	Resistive Element	Other	0.00008402	Ruthenium dioxide	12036-10-1	25%	0.24%	0.95%
				Silver	7440-22-4	40%	0.38%	
				Palladium	7440-05-3	15%	0.14%	
				Lead oxide	1317-36-8	20%	0.19%	
4	Over-Coating	Paint	0.00012255	Epoxy	25068-38-6	100%	1.40%	1.40%
5	Marking	Ink	0.00000437	Epoxy	25068-38-6	100%	0.05%	0.05%
6	End Terminal	Metal	0.00027645	Nickel	7440-02-0	80%	2.54%	3.17%
				Chromium	7440-47-3	20%	0.63%	
7	Ni Plating	Metal	0.00045055	Nickel	7440-02-0	100%	5.16%	5.16%
8	Tin Plating	Metal	0.00036945	Tin	7440-31-5	100%	4.24%	4.24%
		Total weight	0.00872798					

This Document was updated on: **2012/7/23**

Important remarks: Resistive Element contains the Lead (Pb) which can be referred to RoHS Exemption 7(c)-I

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